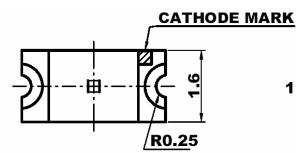


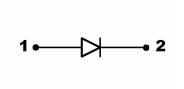
3.2 x 1.6 x 1.1mm SMD LED, Tape & Reel

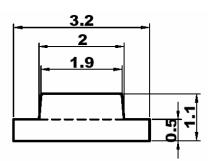
* 3.2 x 1.6 x 1.1mm SMD LED

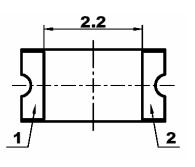
- ✤ 120° VIEWING ANGLE
- ✤ LOW POWER CONSUMPTION
- ✤ LOW CURRENT REQUIREMENT

Package Dimension

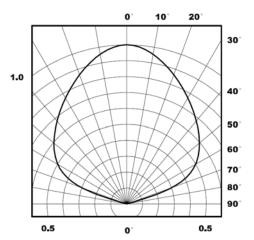








Notes: Unit = mm, Tolerance = ± 0.25 mm



Viewing Angle $2\theta 1/2 = 120^{\circ}$

Part Number	Chip		Long Tung	Iv (IF = 20mA)	
r art Number	Material	Emitted Color	Lens Type	Min (mcd)	Typ (mcd)
L150EC-TR	GaAsP	Red	Water Clear	5	12
				·	·



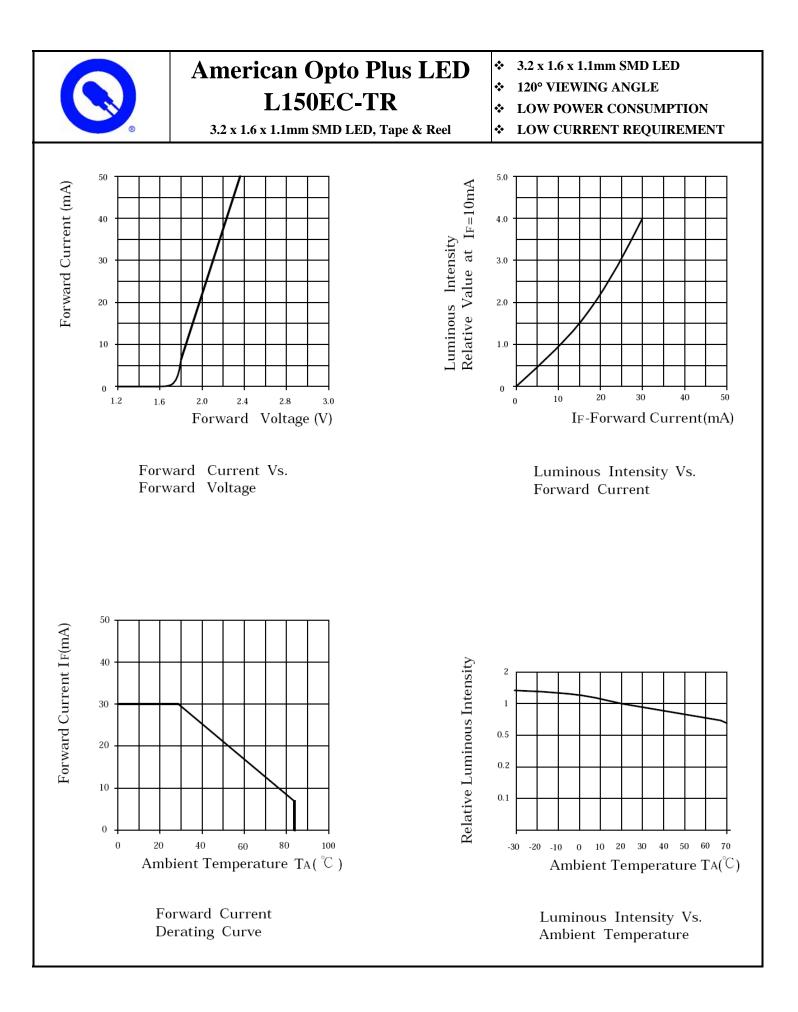
- * 3.2 x 1.6 x 1.1mm SMD LED
- ✤ 120° VIEWING ANGLE
- **♦** LOW POWER CONSUMPTION

3.2 x 1.6 x 1.1mm SMD LED, Tape & Reel

✤ LOW CURRENT REQUIREMENT

Absolute maximum ratings			Unit
(TA=25°C)		(GaAsP)	
Reverse voltage Forward current Forward current(Peak)	V r I f I fp	5 30	V mA
1/10 Duty Cycle,0.1ms Pulse Width Power dissipation LED LAMPS:	P d	100 75	mA mW
Operating temperature Storage temperature LED DISPLAYS:	T op T st	-40~+85 -40~+85	°C °C
Operating temperature Storage temperature	T A T stg	-40~+85 -40~+85	°C °C

Operating characteristics			Unit
(TA=25 [°] C)		(GaAsP)	
Forward voltage(typ.) IF =20mA	V f	2.0	V
Forward voltage(max.) IF =20mA	V f	2.5	V
Reverse current(max.) V _R =5V	IR	10	uA
Wavelength at dominant emission(typ.) IF =20mA	λD	620	nm
Wavelength at peak emission(typ.) IF =20mA	λр	630	nm
Spectral line half-width IF =20mA	Δ λ	45	nm
Capacitance V _F =0V ,f=1MHz	С	12	pF

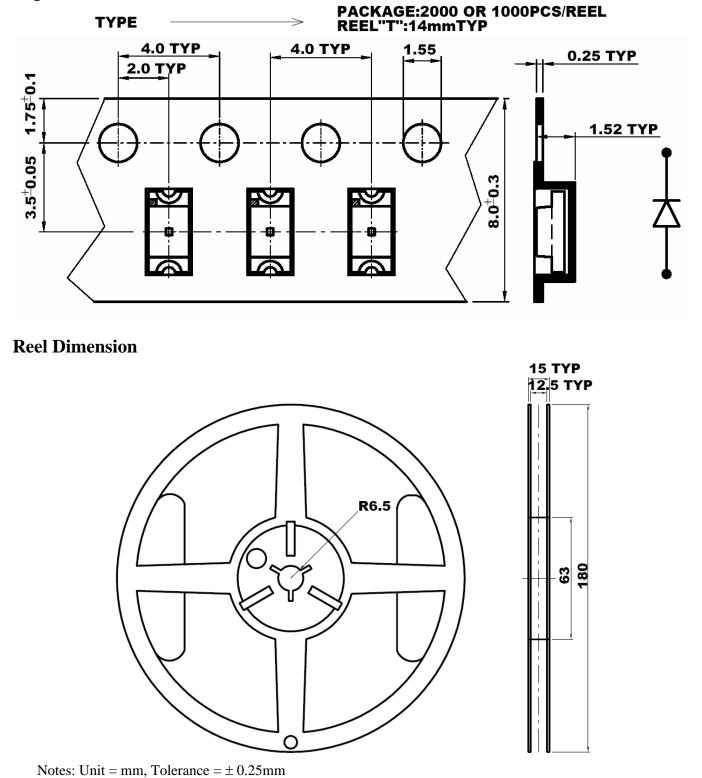




3.2 x 1.6 x 1.1mm SMD LED, Tape & Reel

- * 3.2 x 1.6 x 1.1mm SMD LED
- ✤ 120° VIEWING ANGLE
- ✤ LOW POWER CONSUMPTION
- ✤ LOW CURRENT REQUIREMENT

Tape Dimension

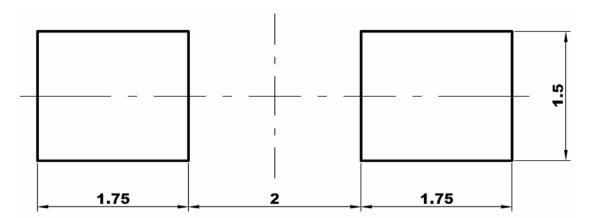




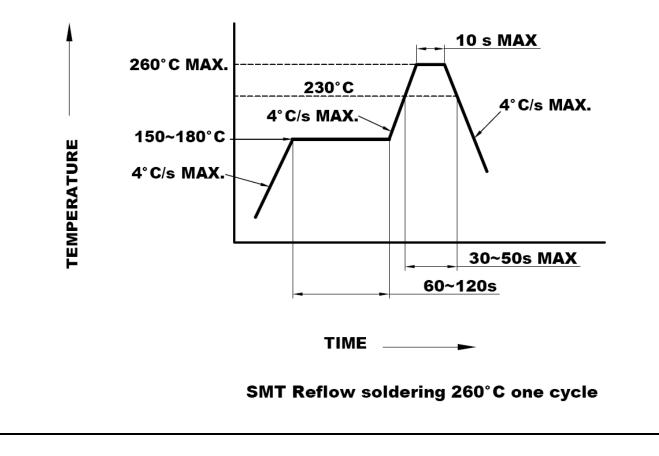
✤ 120° VIEWING ANGLE

- ✤ LOW POWER CONSUMPTION





SMD Reflow Soldering Instructions





* 3.2 x 1.6 x 1.1mm SMD LED

✤ 120° VIEWING ANGLE

✤ LOW POWER CONSUMPTION

3.2 x 1.6 x 1.1mm SMD LED, Tape & Reel

✤ LOW CURRENT REQUIREMENT

SMD Handling and Application Precautions

STORAGE

- 1. It is recommended to store the devices in accordance with the following conditions:
 - a. Humidity: 60% RH Max
 - b. Temperature: $5^{\circ}C \sim 30^{\circ}C (41^{\circ}F \sim 86^{\circ}F)$
- Shelf life in sealed bag: 12 months at < 5°C ~ 30°C and < 60% RH. After the package is opened, products should be used within 72 hours, or they should be kept at ≤ 30% RH in zip-locked sealed bags.

DRY PACK AND BAKING

SMD LEDs are MOISTURE SENSITIVE devices. Avoid absorbing moisture at any time during transportation and/or storage. It is recommended to bake before soldering when the pack is unsealed after 72 hours, or any suspicious moisture being found. Bake devices in accordance with the following conditions:

- 50 \pm 3°C x (12 ~ 24 hours) and < 5% RH, tape and reel type
- $100 \pm 3^{\circ}$ C x (45 min ~ 1 hour), loose packing type, OR
- $130 \pm 3^{\circ}$ C x (15 min ~ 30 min), loose packing type

ELECTROSTATIC DISCHARGE (ESD) PROTECTION

Materials with GaN, InGaN, AlInGaP are STATIC SENSITIVE devices. They will be packed in anti-static bags. ESD protection must be deliberately observed from the initial design stage. Electrostatic discharge may result in severe malfunction of devices. In the event of manual working in process, make sure the devices are well-protected from ESD at any time. Surge before and during handling of products.